

EC3920TTS-33.333M
[Click part number to visit Part Number Details page](#)
REGULATORY COMPLIANCE (Data Sheet downloaded on May 18, 2019)
[Click badges to download compliance docs](#)

Regulatory Compliance standards are subject to updates by governing bodies. Click the badges to download the latest compliance docs for this part number directly from Ecliptek.

**ITEM DESCRIPTION**

Quartz Crystal Clock Oscillators XO (SPXO) LVCMOS (CMOS) 1.8Vdc 4 Pad 3.2mm x 5.0mm Ceramic Surface Mount (SMD) 33.333MHz ± 20 ppm -10°C to +70°C

ELECTRICAL SPECIFICATIONS

Nominal Frequency	33.333MHz
Frequency Tolerance/Stability	± 20 ppm Maximum (Inclusive of all conditions: Calibration Tolerance at 25°C, Frequency Stability over the Operating Temperature Range, Supply Voltage Change, Output Load Change, First Year Aging at 25°C, Shock, and Vibration)
Operating Temperature Range	-10°C to +70°C
Supply Voltage	1.8Vdc $\pm 5\%$
Input Current	4mA Maximum
Output Voltage Logic High (Voh)	90% of Vdd Minimum (IOH = -4mA)
Output Voltage Logic Low (Vol)	10% of Vdd Maximum (IOH = +4mA)
Rise/Fall Time	6nSec Maximum (Measured at 20% to 80% of waveform)
Duty Cycle	50 $\pm 5\%$ (Measured at 50% of waveform)
Load Drive Capability	15pF Maximum
Output Logic Type	CMOS
Pin 1 Connection	Tri-State (High Impedance)
Tri-State Input Voltage (Vih and Vil)	90% of Vdd Minimum or No Connect to Enable Output, 10% of Vdd Maximum to Disable Output (High Impedance)
Standby Current	10 μ A Maximum (Disabled Output: High Impedance)
RMS Phase Jitter	1pSec Maximum (12kHz to 20MHz offset frequency)
Start Up Time	10mSec Maximum
Storage Temperature Range	-55°C to +125°C

ENVIRONMENTAL & MECHANICAL SPECIFICATIONS

ESD Susceptibility	MIL-STD-883, Method 3015, Class 1, HBM: 1500V
Fine Leak Test	MIL-STD-883, Method 1014, Condition A
Flammability	UL94-V0
Gross Leak Test	MIL-STD-883, Method 1014, Condition C
Mechanical Shock	MIL-STD-883, Method 2002, Condition B
Moisture Resistance	MIL-STD-883, Method 1004
Moisture Sensitivity	J-STD-020, MSL 1
Resistance to Soldering Heat	MIL-STD-202, Method 210, Condition K
Resistance to Solvents	MIL-STD-202, Method 215
Solderability	MIL-STD-883, Method 2003
Temperature Cycling	MIL-STD-883, Method 1010, Condition B
Vibration	MIL-STD-883, Method 2007, Condition A

 Click part number to visit
Part Number Details page

Figure 1: Dimensions of the component. The figure shows three views of a component: a top view, a side view, and a bottom view. The top view is a square with rounded corners, with dimensions 3.20 $\pm$ 0.20 (width) and 5.00 $\pm$ 0.20 (height). It features a "MARKING ORIENTATION" label and a circular marking. The side view shows a thickness of 1.3 MAX. The bottom view is a square with rounded corners, with dimensions 1.00 $\pm$ 0.20 (width) and 1.20 $\pm$ 0.20 (height). It features four numbered circular markings (1, 2, 3, 4) and a central square area with dimensions 2.54 $\pm$ 0.15.

LINE	MARKING
1	E33.333 <i>E=Eclipse Designator</i>
2	XXXXX <i>XXXXX=Eclipse Manufacturing Identifier</i>

1-800-ECLIPTEK or 714.433.1200

EC3920TTS-33.333M

[Click part number to visit Part Number Details page](#)

OUTPUT WAVEFORM & TIMING DIAGRAM



EC3920TTS-33.333M

[Click part number to visit Part Number Details page](#)

Test Circuit for CMOS Output



Note 1: An external 0.1µF low frequency tantalum bypass capacitor in parallel with a 0.01µF high frequency ceramic bypass capacitor close to the package ground and V_{DD} pin is required.

Note 2: A low capacitance (<12pF), 10X attenuation factor, high impedance (>10Mohms), and high bandwidth (>300MHz) passive probe is recommended.

Note 3: Capacitance value C_L includes sum of all probe and fixture capacitance.